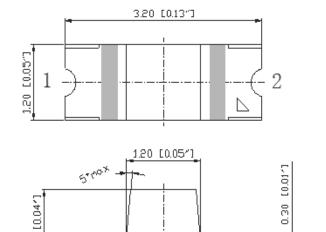
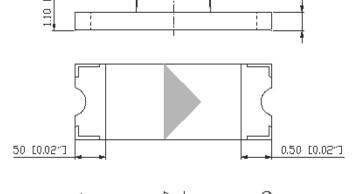


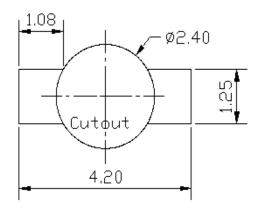
SPECIFICATION CS124ACW2C-R

PACKAGE OUTLINES





RECOMMEND PAD LAYOUT



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ± 0.25mm (0.01") unless otherwised noted.
- 3. Specifications are subject to change without notice.

Part Number	Chip Material	Color of Emission Lens Type		Viewing Angle	
CS124ACW2C-R	InGaN	White	Yellow Diffused	140°	





ABSOLUTE MAXIMUM RATINGS

(TA=25°C)

Parameter	Symbol	Max Rating	Unit	
Forward Current	lF	30	mA	
Reverse Current @ 5V	lR	10	μΑ	
Power Dissipation	Pd	111	mW	
Operating Temperature Range	Тор	-40~+8	°C	
Storage Temperature Range	Тѕтс	-40~+85	°C	
Peak Pulsing Current (1/10 duty f = 10KHz)	lFP	125	mA	
Soldering Temperature	TsoL	Max 260°C for 5 sec Max		

OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25°C)

Darameter	Symbol	Test Condition	Value			Lloit
Parameter			Min	Тур	Max	Unit
Luminous Intensity	lv	IF = 20mA	320	510	1	mcd
Forward Voltage	VF	IF = 20mA	1	3.0	3.7	V
Reverse Leakage Current	lR	VR = 5V	-	-	10	μΑ
Viewing Angle at 50% Iv	201/2	IF = 20mA	1	140	ı	Deg
CIE Coordinates	X	IF = 20mA	1	0.309	1	-
CIE Coordinates	Υ	IF = 20mA	-	0.322	-	-

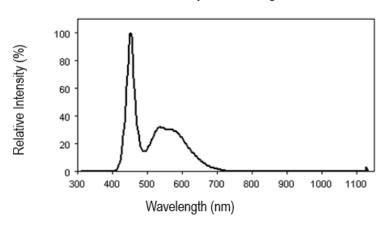
^{*}Tolerance of viewing angle: -10 / +5 deg.



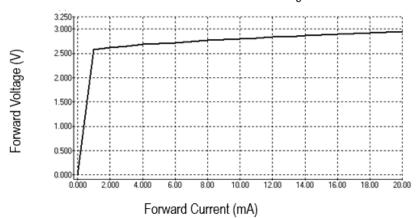


OPTICAL CHARACTERISTIC CURVES

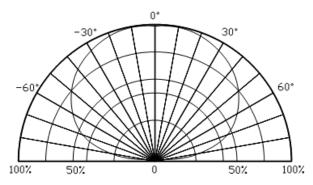
Relative Intensity vs. Wavelength



Forward Current vs. Forward Voltage



Directive Characteristics

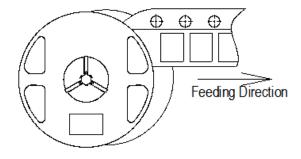




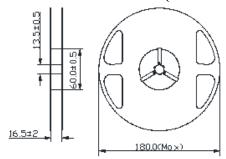


PACKAGING SPECIFICATION

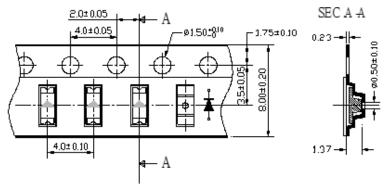
Feeding Direction



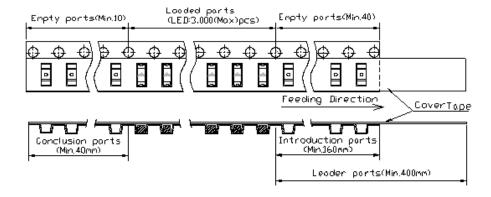
• Dimensions of Reel(Unit: mm)



• Dimensions of Tape(Unit: mm)



Arrangement of Tape



Notes:

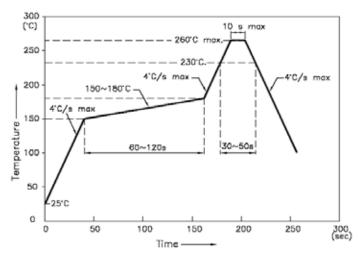
- 1. Empty component pockets are sealed with top cover tape;
- 2. The maximum number of missing lamps is two;
- 3. The cathode is oriented towards the tape sprocket hole.
- 4. 3,000 (Max)pcs/Reel





SOLDERING CONDITIONS

Reflow Temp/Time



- We recommend the reflow temperature 245°C (±5 °C) & the maximum soldering temperature should be limited to 260 °C.
- Do not cause stress to the epoxy resin while it is exposed to high temperature.
- Number of reflow process should be 2 times or less.
- Soldering Iron:
 - Basic spec is ≤ 5 sec when 260 °C. If the temperature is higher, time should be shorter (+10 °C → -1 sec). Power dissipation of iron should be smaller than 20W and temperature should be controllable. Surface temperature of the device should be under 230 °C.
- Rework:
 - Customer must finish rework within 5 sec under 260 °C
 - The head of iron cannot touch copper foil
 - Twin-head type is preferred

